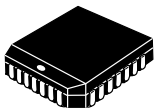
5 V ECL Quint Differential Line Receiver

MC10E116, MC100E116

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PLCC−28
FN SUFFIX
CASE 776−02

Description

The MC10E/100E116 is a quint differential line receiver with emitter-follower outputs. For applications which require bandwidths greater than that of the E116, the E416 device may be of interest.

Active current sources plus a deep collector feature of the MOSAIC III process provide the receivers with excellent common-mode noise rejection. Each receiver has a dedicated V_{CCO} supply lead, providing optimum symmetry and stability.

If both inverting and non-inverting inputs are at an equal potential of > −2.5 V, the receiver does *not* go to a defined state, but rather current-shares in normal differential amplifier fashion, producing output voltage levels midway between HIGH and LOW, or the device may even oscillate.

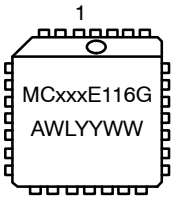
The V_{BB} pin, an internally generated voltage supply, is available to this device only. For single-ended input conditions, the unused differential input is connected to V_{BB} as a switching reference voltage. V_{BB} may also rebias AC coupled inputs. When used, decouple V_{BB} and V_{CC} via a 0.01 μF capacitor and limit current sourcing or sinking to 0.5 mA. When not used, V_{BB} should be left open.

The 100 Series contains temperature compensation.

Features

- 500 ps Max. Propagation Delay
- V_{BB} Supply Output
- Dedicated V_{CCO} Pin for Each Receiver
- PECL Mode Operating Range: V_{CC} = 4.2 V to 5.7 V with V_{EE} = 0 V
- NECL Mode Operating Range: V_{CC} = 0 V with V_{EE} = −4.2 V to −5.7 V
- Output Qs will default low when inputs are < V_{CC} −2.5 V
- Internal Input 50 kΩ Pulldown Resistors
- Meets or Exceeds JEDEC Spec EIA/JESD78 IC Latchup Test
- ESD Protection:
  - > 2 kV Human Body Model
  - > 200 V Machine Model
- Moisture Sensitivity: Level 3 (Pb-Free)
  (For Additional Information, see Application Note AND8003/D)
- Flammability Rating: UL 94 V−0 @ 0.125 in,
  Oxygen Index: 28 to 34
- Transistor Count = 98 Devices
- These Devices are Pb-Free, Halogen Free and are RoHS Compliant

MARKING DIAGRAM*



xxx	= 10 or 100
A	= Assembly Location
WL	= Wafer Lot
YY	= Year
WW	= Work Week
G	= Pb-Free Package

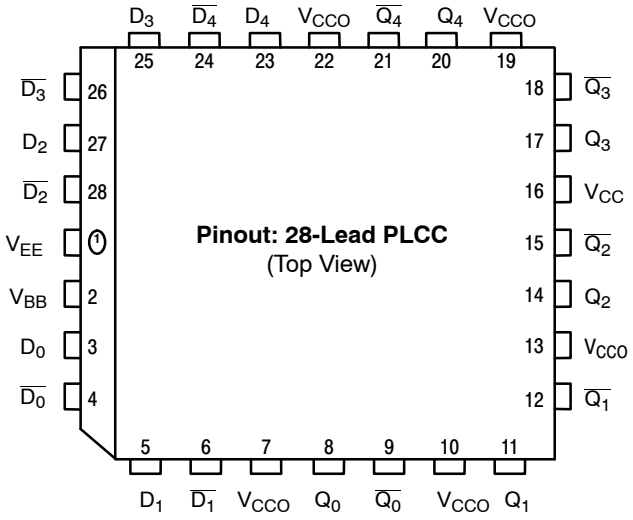
*For additional marking information, refer to Application Note AND8002/D.

ORDERING INFORMATION

Device	Package	Shipping†
MC10E116FNG	PLCC−28 (Pb-Free)	37 Units/Tube
MC100E116FNG	PLCC−28 (Pb-Free)	37 Units/Tube
MC100E116FNR2G	PLCC−28 (Pb-Free)	500 Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

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* All V_{CC} and V_{CCO} pins are tied together on the die.

Warning: All V_{CC}, V_{CCO}, and V_{EE} pins must be externally connected to Power Supply to guarantee proper operation.

Figure 1. Pinout Assignment

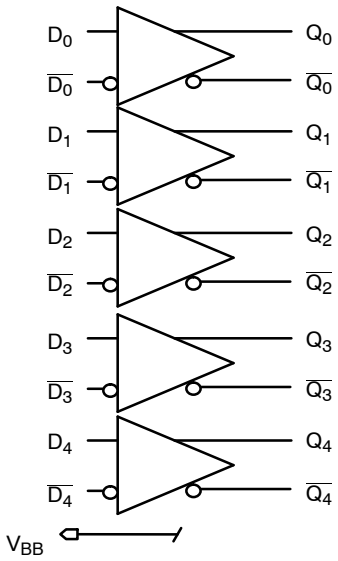


Figure 2. Logic Diagram

Table 1. PIN DESCRIPTION

PIN	FUNCTION
D_0, $\overline{D_0}$ – D_4, $\overline{D_4}$	ECL Differential Input Pairs
Q_0, $\overline{Q_0}$ – Q_4, $\overline{Q_4}$	ECL Differential Output Pairs
V_{BB}	Reference Voltage Output.
V_{CC}, V_{CCO}	Positive Supply
V_{EE}	Negative Supply

Table 2. MAXIMUM RATINGS

Symbol	Parameter	Condition 1	Condition 2	Rating	Unit
V_{CC}	PECL Mode Power Supply	V_{EE} = 0 V		8	V
V_{EE}	NECL Mode Power Supply	V_{CC} = 0 V		–6	V
V_I	PECL Mode Input Voltage NECL Mode Input Voltage	V_{EE} = 0 V V_{CC} = 0 V	$V_I \le V_{CC}$ $V_I \ge V_{EE}$	6 –6	V
I_{out}	Output Current	Continuous Surge		50 100	mA
I_{BB}	V_{BB} Sink/Source			±0.5	mA
T_A	Operating Temperature Range			0 to +85	°C
T_{stg}	Storage Temperature Range			–65 to +150	°C
θ_{JA}	Thermal Resistance (Junction-to-Ambient)	0 lfpm 500 lfpm	PLCC–28 PLCC–28	63.5 43.5	°C/W
θ_{JC}	Thermal Resistance (Junction-to-Case)	Standard Board	PLCC–28	22 to 26	°C/W
T_{sol}	Wave Solder (Pb-Free)			265	°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

Table 3. 10E SERIES PECL DC CHARACTERISTICS (V_{CCx} = 5.0 V, V_{EE} = 0.0 V (Note 1))

Symbol	Characteristic	−40°C			0°C			25°C			85°C			Unit
		Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
I_{EE}	Power Supply Current		29	35		29	35		29	35		29	35	mA
V_{OH}	Output HIGH Voltage (Note 2)				3980	4070	4160	4020	4105	4190	4090	4185	4280	mV
V_{OL}	Output LOW Voltage (Note 2)				3050	3210	3370	3050	3210	3370	3050	3227	3405	mV
V_{IH}	Input HIGH Voltage (Single-Ended)				3830	3995	4160	3870	4030	4190	3940	4110	4280	mV
V_{IL}	Input LOW Voltage (Single-Ended)				3050	3285	3520	3050	3285	3520	3050	3302	3555	mV
V_{BB}	Output Voltage Reference	3.57		3.7	3.57		3.7	3.65		3.75	3.69		3.81	V
V_{IHCMR}	Input HIGH Voltage Common Mode Range (Differential Configuration) (Note 3)				2.2		4.4	2.2		4.4	2.2		4.4	V
I_{IH}	Input HIGH Current			200			200			200			200	μA
I_{IL}	Input LOW Current				0.5	0.3		0.5	0.25		0.3	0.2		μA

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfpm.

1. Input and output parameters vary 1:1 with V_{CC}. V_{EE} can vary −0.46 V / +0.06 V.
2. Outputs are terminated through a 50 Ω resistor to V_{CC} − 2.0 V.
3. V_{IHCMR} min varies 1:1 with V_{EE}, max varies 1:1 with V_{CC}.

Table 4. 10E SERIES NECL DC CHARACTERISTICS (V_{CCx} = 0.0 V; V_{EE} = −5.0 V (Note 1))

Symbol	Characteristic	−40°C			0°C			25°C			85°C			Unit
		Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
I_{EE}	Power Supply Current		29	35		29	35		29	35		29	35	mA
V_{OH}	Output HIGH Voltage (Note 2)				−1020	−930	−840	−980	−895	−810	−910	−815	−720	mV
V_{OL}	Output LOW Voltage (Note 2)				−1950	−1790	−1630	−1950	−1790	−1630	−1950	−1773	−1595	mV
V_{IH}	Input HIGH Voltage (Single-Ended)				−1170	−1005	−840	−1130	−970	−810	−1060	−890	−720	mV
V_{IL}	Input LOW Voltage (Single-Ended)				−1950	−1715	−1480	−1950	−1715	−1480	−1950	−1698	−1445	mV
V_{BB}	Output Voltage Reference	−1.43		−1.3	−1.13		−1.30	−1.35		−1.25	−1.31		−1.19	V
V_{IHCMR}	Input HIGH Voltage Common Mode Range (Differential Configuration) (Note 3)				−2.8		−0.6	−2.8		−0.6	−2.8		−0.6	V
I_{IH}	Input HIGH Current			200			200			200			200	μA
I_{IL}	Input LOW Current				0.5	0.3		0.5	0.065		0.3	0.2		μA

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfpm.

1. Input and output parameters vary 1:1 with V_{CC}. V_{EE} can vary −0.46 V / +0.06 V.
2. Outputs are terminated through a 50 Ω resistor to V_{CC} − 2.0 V.
3. V_{IHCMR} min varies 1:1 with V_{EE}, max varies 1:1 with V_{CC}.

Table 5. 100E SERIES PECL DC CHARACTERISTICS (V_{CCx} = 5.0 V, V_{EE} = 0.0 V (Note 1))

Symbol	Characteristic	−40°C			0°C			25°C			85°C			Unit
		Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
I_{EE}	Power Supply Current		29	35		29	35		29	35		29	35	mA
I_{EE}	Power Supply Current		29	35		29	35		29	35		29	40	mA
V_{OH}	Output HIGH Voltage (Note 2)				3975	4050	4120	3975	4050	4120	3975	4050	4120	mV
V_{OL}	Output LOW Voltage (Note 2)				3190	3295	3380	3190	3255	3380	3190	3260	3380	mV
V_{IH}	Input HIGH Voltage (Single-Ended)		3975		3835	3975	4120	3835	3975	4120	3835	3975	4120	mV
V_{IL}	Input LOW Voltage (Single-Ended)		3355		3190	3355	3525	3190	3355	3525	3190	3355	3525	mV
V_{BB}	Output Voltage Reference	3.62		3.74	3.64		3.75	3.62		3.74	3.62		3.74	V
V_{IHCMR}	Input HIGH Voltage Common Mode Range (Differential Configuration) (Note 3)				2.2		4.4	2.2		4.4	2.2		4.4	V
I_{IH}	Input HIGH Current			200			200			200			200	μA
I_{IL}	Input LOW Current				0.5	0.3		0.5	0.25		0.5	0.2		μA

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfpm.

1. Input and output parameters vary 1:1 with V_{CC}. V_{EE} can vary −0.46 V / +0.8 V.
2. Outputs are terminated through a 50 Ω resistor to V_{CC} − 2.0 V.
3. V_{IHCMR} min varies 1:1 with V_{EE}, max varies 1:1 with V_{CC}.

Table 6. 100E SERIES NECL DC CHARACTERISTICS (V_{CCx} = 0.0 V; V_{EE} = −5.0 V (Note 1))

Symbol	Characteristic	−40°C			0°C			25°C			85°C			Unit
		Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
I_{EE}	Power Supply Current		29	35		29	35		29	35		29	40	mA
V_{OH}	Output HIGH Voltage (Note 2)				−1025	−950	−880	−1025	−950	−880	−1025	−950	−880	mV
V_{OL}	Output LOW Voltage (Note 2)				−1810	−1705	−1620	−1810	−1745	−1620	−1810	−1740	−1620	mV
V_{IH}	Input HIGH Voltage (Single-Ended)		−1025		−1165	−1025	−880	−1165	−1025	−880	−1165	−1025	−880	mV
V_{IL}	Input LOW Voltage (Single-Ended)		−1645		−1810	−1645	−1475	−1810	−1645	−1475	−1810	−1645	−1475	mV
V_{BB}	Output Voltage Reference	−1.38		−1.26	−1.38		−1.25	−1.38		−1.26	−1.38		−1.26	V
V_{IHCMR}	Input HIGH Voltage Common Mode Range (Differential Configuration) (Note 3)				−2.8		−0.6	−2.8		−0.6	−2.8		−0.6	V
I_{IH}	Input HIGH Current			200			200			200			200	μA
I_{IL}	Input LOW Current				0.5	0.3		0.5	0.25		0.5	0.2		μA

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfpm.

1. Input and output parameters vary 1:1 with V_{CC}. V_{EE} can vary −0.46 V / +0.8 V.
2. Outputs are terminated through a 50 Ω resistor to V_{CC} − 2.0 V.
3. V_{IHCMR} min varies 1:1 with V_{EE}, max varies 1:1 with V_{CC}.

Table 7. AC CHARACTERISTICS (V_{CCx}= 5.0 V; V_{EE} = 0.0 V or V_{CCx} = 0.0 V; V_{EE} = −5.0 V (Note 1))

Symbol	Characteristic	−40°C			25°C			85°C			Unit
		Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
f_{MAX}	Maximum Toggle Frequency		800			800			800		MHz
t_{PLH} t_{PHL}	Propagation Delay to Output D (Differential Configuration) D (Single-Ended)	 150 150	 300 300	 500 550	 200 150	 300 300	 450 500	 200 150	 300 300	 450 500	ps
t_{skew}	Within-Device Skew (Note 2)		50			50			50		ps
t_{skew}	Duty Cycle Skew (Note 3) $t_{PLH} - t_{PHL}$		±10			±10			±10		ps
t_{JITTER}	Random Clock Jitter (RMS)		< 1			< 1			< 1		ps
V_{PP}	Input Voltage Swing (Differential Configuration)	150			150			150			mV
t_r/t_f	Rise/Fall Time 20−80%	250	375	625	275	375	575	275	375	575	ps

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfpm.

1. 10 Series: V_{EE} can vary −0.46 V / +0.06 V.
   100 Series: V_{EE} can vary −0.46 V / +0.8 V.
2. Within-device skew is defined as identical transitions on similar paths through a device.
3. Duty cycle skew is defined only for differential operation when the delays are measured from the cross point of the inputs to the cross point of the outputs.

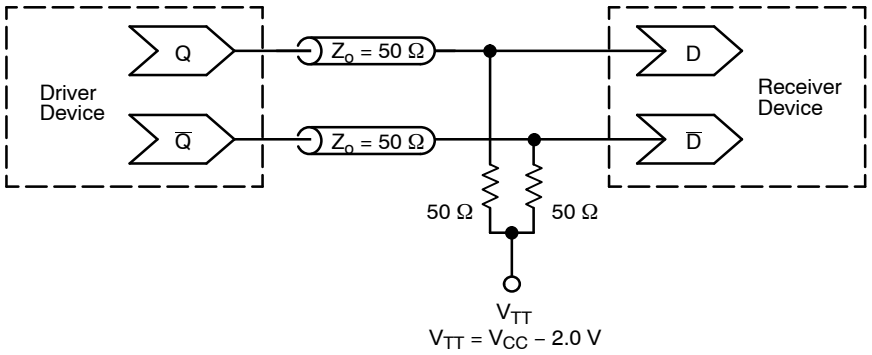


Figure 3. Typical Termination for Output Driver and Device Evaluation (See Application Note AND8020/D – Termination of ECL Logic Devices)

Resource Reference of Application Notes

AN1405/D – ECL Clock Distribution Techniques

AN1406/D – Designing with PECL (ECL at +5.0 V)

AN1503/D – ECLinPS™ I/O SPiCE Modeling Kit

AN1504/D – Metastability and the ECLinPS Family

AN1568/D – Interfacing Between LVDS and ECL

AN1672/D – The ECL Translator Guide

AND8001/D – Odd Number Counters Design

AND8002/D – Marking and Date Codes

AND8020/D – Termination of ECL Logic Devices

AND8066/D – Interfacing with ECLinPS

AND8090/D – AC Characteristics of ECL Devices

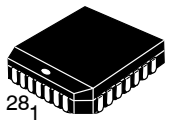
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MECHANICAL CASE OUTLINE
PACKAGE DIMENSIONS

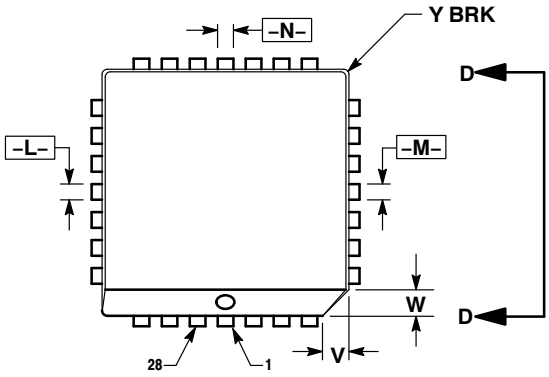
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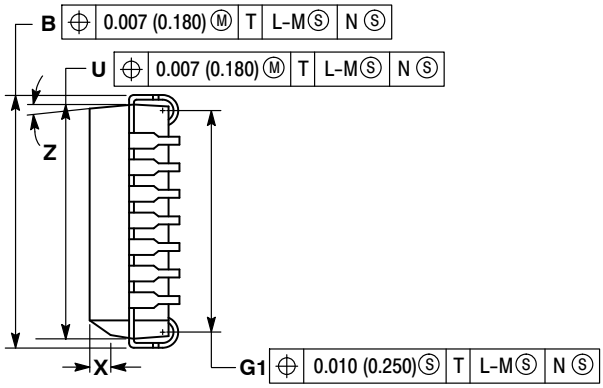
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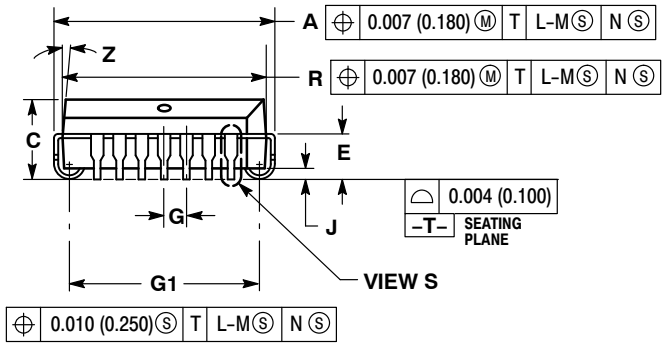


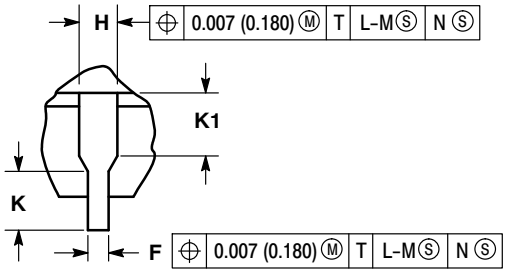
SCALE 1:1





VIEW D–D



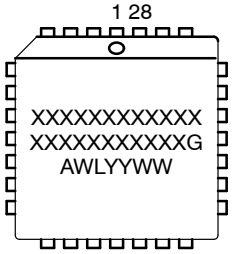


VIEW S

NOTES:
1. DATUMS –L–, –M–, AND –N– DETERMINED WHERE TOP OF LEAD SHOULDER EXITS PLASTIC BODY AT MOLD PARTING LINE.
2. DIMENSION G1, TRUE POSITION TO BE MEASURED AT DATUM –T–, SEATING PLANE.
3. DIMENSIONS R AND U DO NOT INCLUDE MOLD FLASH. ALLOWABLE MOLD FLASH IS 0.010 (0.250) PER SIDE.
4. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
5. CONTROLLING DIMENSION: INCH.
6. THE PACKAGE TOP MAY BE SMALLER THAN THE PACKAGE BOTTOM BY UP TO 0.012 (0.300). DIMENSIONS R AND U ARE DETERMINED AT THE OUTERMOST EXTREMES OF THE PLASTIC BODY EXCLUSIVE OF MOLD FLASH, TIE BAR BURRS, GATE BURRS AND INTERLEAD FLASH, BUT INCLUDING ANY MISMATCH BETWEEN THE TOP AND BOTTOM OF THE PLASTIC BODY.
7. DIMENSION H DOES NOT INCLUDE DAMBAR PROTRUSION OR INTRUSION. THE DAMBAR PROTRUSION(S) SHALL NOT CAUSE THE H DIMENSION TO BE GREATER THAN 0.037 (0.940). THE DAMBAR INTRUSION(S) SHALL NOT CAUSE THE H DIMENSION TO BE SMALLER THAN 0.025 (0.635).

	INCHES		MILLIMETERS	
DIM	MIN	MAX	MIN	MAX
A	0.485	0.495	12.32	12.57
B	0.485	0.495	12.32	12.57
C	0.165	0.180	4.20	4.57
E	0.090	0.110	2.29	2.79
F	0.013	0.021	0.33	0.53
G	0.050 BSC		1.27 BSC	
H	0.026	0.032	0.66	0.81
J	0.020	---	0.51	---
K	0.025	---	0.64	---
R	0.450	0.456	11.43	11.58
U	0.450	0.456	11.43	11.58
V	0.042	0.048	1.07	1.21
W	0.042	0.048	1.07	1.21
X	0.042	0.056	1.07	1.42
Y	---	0.020	---	0.50
Z	2°	10°	2°	10°
G1	0.410	0.430	10.42	10.92
K1	0.040	---	1.02	---

GENERIC MARKING DIAGRAM*



XXXXX = Specific Device Code
A = Assembly Location
WL = Wafer Lot
YY = Year
WW = Work Week
G = Pb−Free Package

*This information is generic. Please refer to device data sheet for actual part marking. Pb−Free indicator, “G” or microdot “ ▪”, may or may not be present.

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